SN74ABTE16246
11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER
WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS

- Member of the Texas Instruments Widebus™ Family

- Supports the VME64 ETL Specification

- Reduced TTL-Compatible Input Threshold Range

- High-Drive Outputs (I_{OH} = –60 mA, I_{OL} = 90 mA) Support Equivalent 25-Ω Incident-Wave Switching

- V_{CC}BIAS Pin Minimizes Signal Distortion During Live Insertion

- Internal Pullup Resistor on $\overline{OE}$ Keeps Outputs in High-Impedance State During Power Up or Power Down

- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise

- Equivalent 25-Ω Series Damping Resistor on B Port

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors

DGG OR DL PACKAGE
(TOP VIEW)

11$\overline{OE}$	1		48	V_{CC}BIAS
11DIR	2		47	11A
11B	3		46	10DIR
GND	4		45	GND
10B	5		44	10A
9B	6		43	9A
V_{CC}	7		42	V_{CC}
8BI	8		41	9DIR
8BO	9		40	8A
GND	10		39	GND
7BO	11		38	7A
6BI	12		37	7BI
6BO	13		36	6A
5BO	14		35	5A
GND	15		34	GND
4BO	16		33	5BI
4BI	17		32	4A
V_{CC}	18		31	V_{CC}
3BO	19		30	3A
2BI	20		29	3BI
GND	21		28	GND
2BO	22		27	2A
1BO	23		26	1A
1BI	24		25	$\overline{OE}$

description/ordering information

The SN74ABTE16246 is an 11-bit noninverting transceiver designed for asynchronous two-way communication between buses. This device has open-collector and 3-state outputs. The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated. When $\overline{OE}$ is low, the device is active.

The B port has an equivalent 25-Ω series output resistor to reduce ringing. Active bus-hold inputs on the B port hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via V_{CC}BIAS, which establishes a voltage between 1.3 V and 1.7 V when V_{CC} is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74ABTE16246DL	ABTE16246
		Tape and reel	SN74ABTE16246DLR	
	TSSOP – DGG	Tape and reel	SN74ABTE16246DGGR	ABTE16246

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

FUNCTION TABLE

INPUTS					OPERATION
$\overline{OE}$	9DIR	10DIR	11DIR	11$\overline{OE}$	
H	X	X	X	X	Isolation
L	X	X	X	X	1BI–8BI data to 1A–8A bus (OC†), 1A–8A data to 1BO–8BO bus
L	L	X	X	X	9A data to 9B bus
L	H	X	X	X	9B data to 9A bus
L	X	L	X	X	10A data to 10B bus
L	X	H	X	X	10B data to 10A bus
L	X	X	L	L	11A data to 11B bus
L	X	X	L	H	11A, 11B isolation
L	X	X	H	X	11B data to 11A bus

† OC = Open-collector outputs

logic diagram (positive logic)

To Seven Other Channels
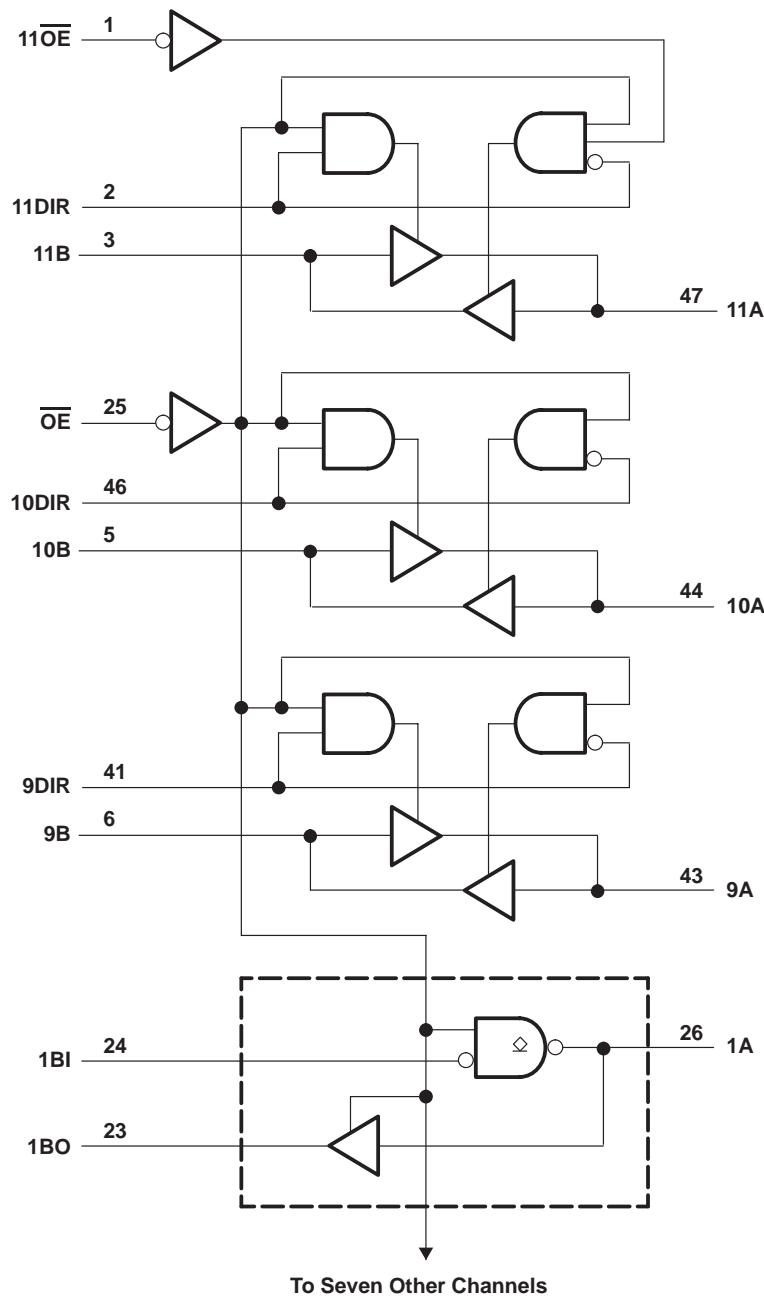
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} and V_{CC}BIAS	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O	128 mA
Input clamp current, I_{IK} (V_I < 0)	–18 mA
Output clamp current, I_{OK} (V_O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}, V_{CC}BIAS	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage	$\overline{OE}$	2			V
		Except $\overline{OE}$	1.6			
V_{IL}	Low-level input voltage	$\overline{OE}$			0.8	V
		Except $\overline{OE}$			1.4	
V_{OH}	High-level output voltage	1A–8A	0		5.5	V
V_I	Input voltage		0		V_{CC}	V
I_{OH}	High-level output current	B bus			–12	mA
		9A–11A			–64	
I_{OL}	Low-level output current	B bus			12	mA
		A bus			90	
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
T_A	Operating free-air temperature		–40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}		$V_{CC} = 4.5$ V,	$I_I = -18$ mA			−1.2	V
V_{OH}	B port	$V_{CC} = 5.5$ V,	$I_{OH} = -100$ μA			V_{CC}−0.2	V
		$V_{CC} = 4.5$ V	$I_{OH} = -1$ mA	2.4			
			$I_{OH} = -12$ mA	2			
	9A–11A	$V_{CC} = 5.5$ V,	$I_{OH} = -1$ mA			4.5	
		$V_{CC} = 4.5$ V	$I_{OH} = -32$ mA	2.4			
			$I_{OH} = -64$ mA	2			
I_{OH}	1A–8A	$V_{CC} = 4.5$ V,	$V_{OH} = 5.5$ V			20	μA
V_{OL}	B port	$V_{CC} = 4.5$ V	$I_{OL} = 1$ mA			0.4	V
			$I_{OL} = 12$ mA			0.8	
	A port	$V_{CC} = 4.5$ V	$I_{OL} = 64$ mA			0.55	
			$I_{OL} = 90$ mA			0.9	
V_{hys}					100		mV
$I_{I(hold)}$	B port	$V_{CC} = 4.5$ V	$V_I = 0.8$ V	100			μA
			$V_I = 2$ V	−100			
		$V_{CC} = 5.5$ V,	$V_I = 0$ to 5.5 V			±500	
I_I	Control inputs	$V_{CC} = 5.5$ V	$V_I = V_{CC}$ or GND			±1	μA
	A or B ports	$V_{CC} = 5.5$ V, $\overline{OE} = V_{CC}$				±20	
I_{OZH}‡	9A–11A	$V_{CC} = 5.5$ V,	$V_O = 2.7$ V			10	μA
I_{OZL}‡	9A–11A	$V_{CC} = 5.5$ V,	$V_O = 0.5$ V			−10	μA
I_O	A port	$V_{CC} = 5.5$ V,	$V_O = 2.5$ V	−50		−180	mA
	B port			−25		−90	
I_{off}		$V_{CC} = 0$, V_I or $V_O \le 4.5$ V,	V_{CC}BIAS = 0			±100	μA
I_{CC}	A or B ports	$V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND	Outputs high		28	36	mA
			Outputs low		38	48	
			Outputs disabled		20	32	
I_{CCD}	A or B ports	$V_{CC} = 5$ V, $C_L = 50$ pF	$\overline{OE}$ high		0.02		mA/ MHz
			$\overline{OE}$ low		0.33		
C_i	Control inputs	$V_I = 2.5$ V or 0.5 V			2.5	4	pF
C_{io}	I/O ports	$V_O = 2.5$ V or 0.5 V			4.5	8	pF

† All typical values are at $V_{CC} = 5$ V, $T_A = 25°$C.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

live-insertion specifications over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS			MIN	TYP[†]	MAX	UNIT
I_{CC} (V_{CC}BIAS)		V_{CC} = 0 to 4.5 V,	V_{CC}BIAS = 4.5 V to 5.5 V,	$I_{O(DC)}$ = 0		250	700	μA
		V_{CC} = 4.5 V to 5.5 V[‡],	V_{CC}BIAS = 4.5 V to 5.5 V,	$I_{O(DC)}$ = 0			20	
V_O	A port	V_{CC} = 0	V_{CC}BIAS = 4.5 V to 5.5 V		1.1	1.5	1.9	V
			V_{CC}BIAS = 4.75 V to 5.25 V		1.3	1.5	1.7	
I_O	A port	V_{CC} = 0,	V_{CC}BIAS = 4.5 V	V_O = 0	−20		−100	μA
				V_O = 3 V	20		100	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[‡] V_{CC} − 0.5 V < V_{CC}BIAS

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	B	1.5	3.1	4.2	1.5	5.2	ns
t_{PHL}			1.5	3.5	4.6	1.5	5.2	
t_{PLH}	9B–11B	9A–11A	1.5	3	3.8	1.5	4.5	ns
t_{PHL}			1.5	3.2	4	1.5	4.5	
t_{PLH}[§]	1B–8B	1A–8A	1.5	3.2	4	1.5	4.5	ns
t_{PLH}[¶]			7.5	8.9	9.7	7.5	10.3	
t_{PHL}			1.5	3.2	4	1.5	4.5	
t_{PZH}	$\overline{OE}$	9A–11A	2	4.3	5.3	2	6.2	ns
t_{PZL}		1A–11A	2	4.4	5.4	2	6.8	
t_{PZH}	$\overline{OE}$	B	2	4.3	6	2	7.1	ns
t_{PZL}			2	4.5	6.4	2	7.3	
t_{PHZ}	$\overline{OE}$	9A–11A	2	4.2	5.9	2	6.7	ns
t_{PLZ}		1A–11A	2	3.5	4.6	2	5.1	
t_{PHZ}	$\overline{OE}$	B	2.5	4.3	6.2	2.5	7	ns
t_{PLZ}			2	3.6	5	2	5.5	

[§] Measurement point is V_{OL} + 0.3 V.
[¶] Measurement point is V_{OL} + 1.5 V.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD	V_{CC} = 5 V, T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
t_{PLH}	9B–11B	9A–11A	R_X = 13 Ω	1.5	3.2	4	1.5	4.8	ns
t_{PHL}				1.5	3.8	4.7	1.5	5.6	
t_{PHL}	1B–8B	1A–8A	R_X = 13 Ω	1.5	3.3	4.2	1.5	4.8	ns
t_{PLH}	9B–11B	9A–11A	R_X = 26 Ω	1.5	3.1	4	1.5	4.6	ns
t_{PHL}				1.5	3.5	4.4	1.5	4.9	
t_{PHL}	1B–8B	1A–8A	R_X = 26 Ω	1.5	3.1	4	1.5	4.4	ns
t_{PLH}	9B–11B	1A–8A	R_X = 56 Ω	1.5	3	3.8	1.5	4.5	ns
t_{PHL}				1.5	3.3	4.2	1.5	4.7	
t_{PHL}	1B–8B	1A–8A	R_X = 56 Ω	1.5	3	4	1.5	4.4	ns
$t_{sk(p)}$	B	A	R_X = Open		0.1	0.6		2	ns
	A	B	R_X = Open		0.4	0.8		2	
	B	A	R_X = 26 Ω		0.3	0.8		2	
$t_{sk(o)}$	B	A	R_X = Open		0.3	0.7		1.3	ns
	A	B	R_X = Open		0.7	1.1		1.3	
	B	A	R_X = 26 Ω		0.5	1		1.3	
t_t†	B	A	R_X = 26 Ω	0.5	0.8	1.5	0.5	1.5	ns
t_t‡	A	B	R_X = Open	3.5	5.5	7.3	3.5	7.9	ns

† t_t is measured between 1 V and 2 V of the output waveform.
‡ t_t is measured between 10% and 90% of the output waveform.

extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LOAD	MIN	MAX	UNIT
$t_{sk(temp)}$	A	B	V_{CC} = constant, ΔT_A = 20°C			2.5	ns
	B	A		R_X = 56 Ω		4	
$t_{sk(load)}$	B	A	V_{CC} = constant, Temperature = constant	R_X = 13, 26, or 56 Ω		4	ns

PARAMETER MEASUREMENT INFORMATION
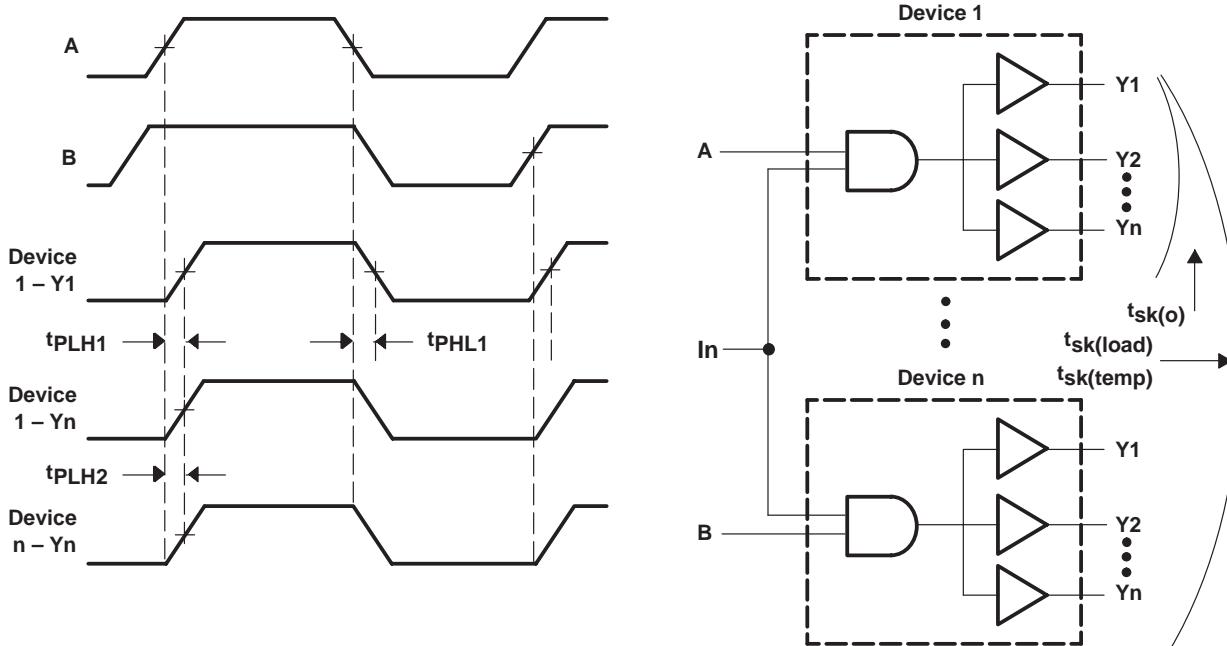
NOTES: A. Pulse skew, $t_{sk(p)}$, is defined as the difference in propagation-delay times t_{PLH1} and t_{PHL1} on the same terminal at identical operating conditions.

B. Output skew, $t_{sk(o)}$, is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g., $|t_{PLH1} - t_{PLH2}|$) .

C. Temperature skew, $t_{sk(temp)}$, is the output skew of two devices, both having the same value of $V_{CC} \pm 1\%$ and with package temperature differences of 20°C.

D. Load skew, $t_{sk(load)}$, is measured with R_X in Figure 2 at 13 Ω for one unit and 56 Ω for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics

TEXAS
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POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION
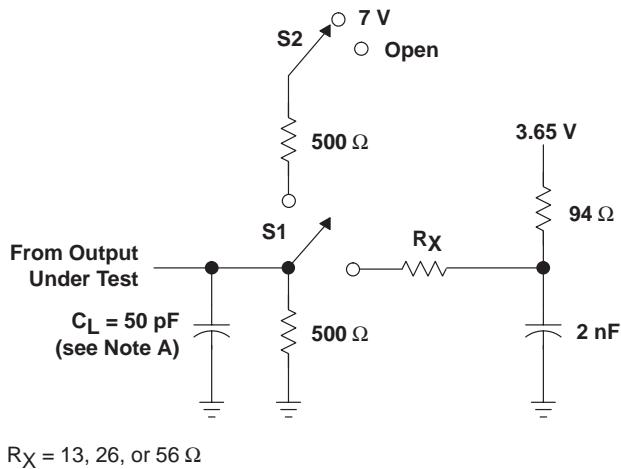
SWITCHING TABLE LOADS	S1	S2
t_{PLH}/t_{PHL} (9A–11A and B port)	Up	Open
t_{PLH}/t_{PHL} (1A–8A)	Up	7 V
t_{PLZ}/t_{PZL}	Up	7 V
t_{PHZ}/t_{PZH} (except 1A–8A)	Up	Open

EXTENDED SWITCHING TABLE LOADS	S1	S2
$t_{PLH}/t_{PHL}/t_{sk}$ (A port)	Down	X
$t_{PLH}/t_{PHL}/t_{sk}$ (B port)	Up	Open
t_t (A port) (see Note E)	Down	X
t_t (B port) (see Note F)	Up	Open

R_X = 13, 26, or 56 Ω

LOAD CIRCUIT

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
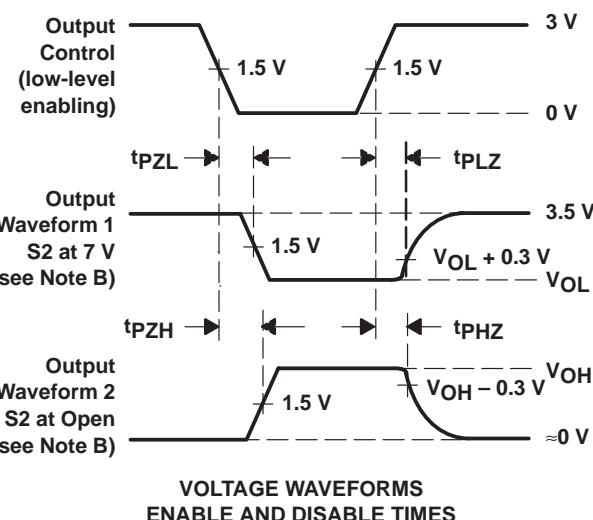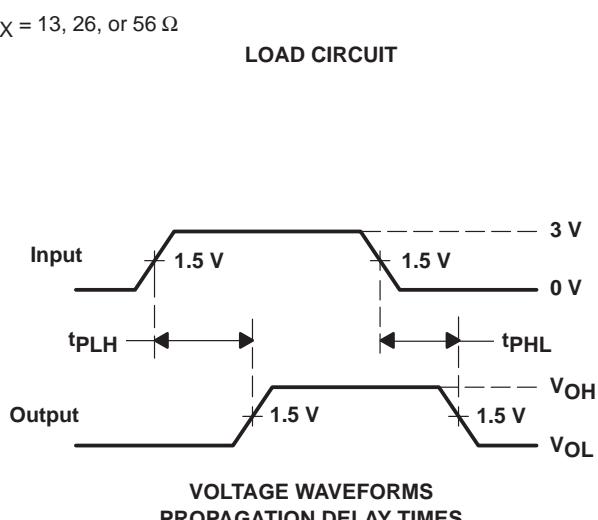
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_t is measured between 1 V and 2 V of the output waveform.
F. t_t is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74ABTE16246DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABTE16246DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16246DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16246DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16246DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16246DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABTE16246DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

Cavity
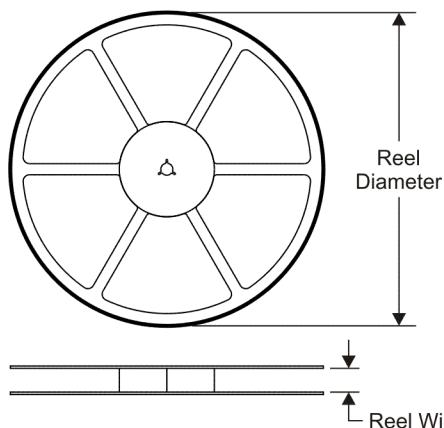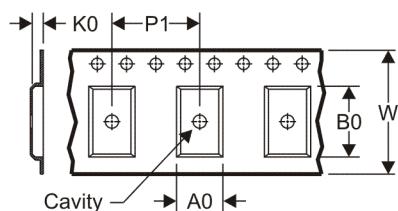
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

User Direction of Feed

Pocket Quadrants
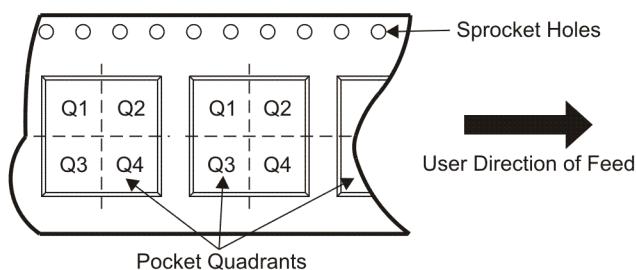
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABTE16246DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS
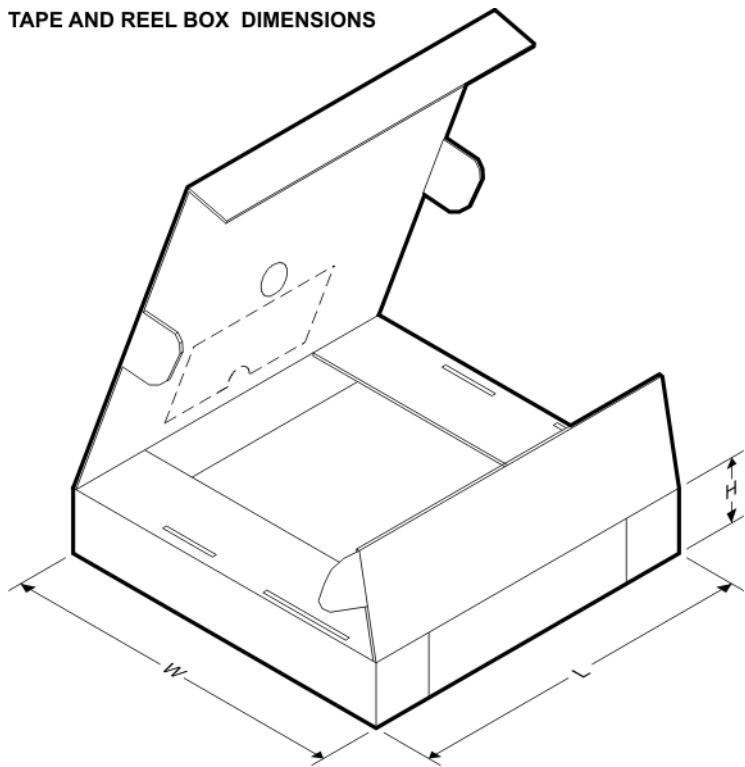
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74ABTE16246DLR	SSOP	DL	48	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)　　　　　　　　　　　　　　**PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078 / F 12/97
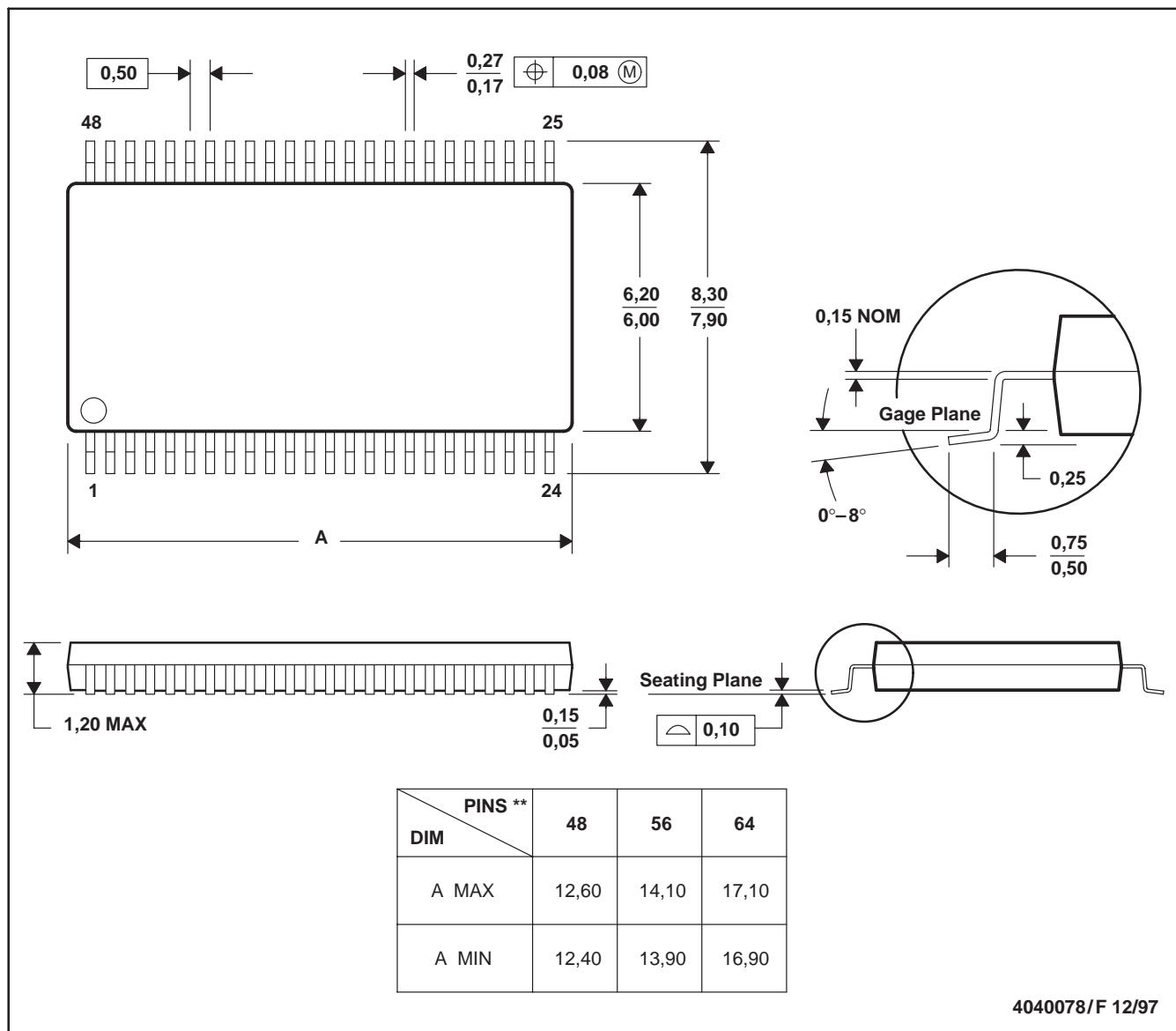
NOTES: A. All linear dimensions are in millimeters.
　　　　B. This drawing is subject to change without notice.
　　　　C. Body dimensions do not include mold protrusion not to exceed 0,15.
　　　　D. Falls within JEDEC MO-153

MECHANICAL DATA

DL (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048 / E 12/01
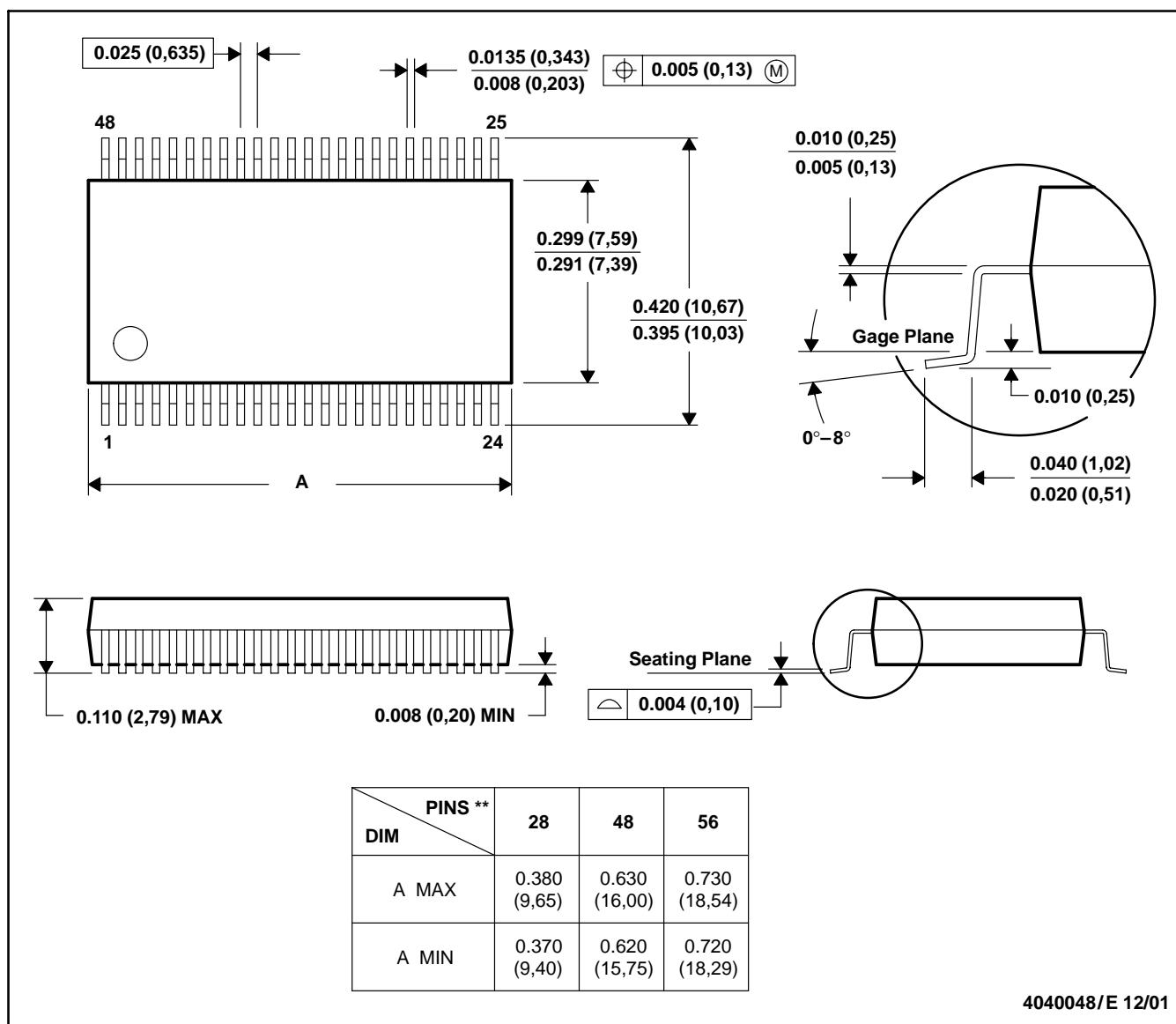
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO-118

TEXAS INSTRUMENTS

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